

Diamond Wire Saw

Advantages of Coolant

Excellent cooling capability and detergency (sludge discharging) at the breakpoint by high osmotic strength and excellent surface tension, supporting wire-saw's high speed high load cutting. Promoting stable production of high-quality wafer by optimizing lubricity, sludge dispersibility, anti-foaming, oil separating and rust prevention.

Lapping Vehicle

Advantages

Having excellent abrasive coating dispersibility and sedimentation prevention by special water-soluble polymer compounded. It will result stable lap processing and rate improving, as well as protecting surface plate (FCD450) from rust by rust preventing Performance.

	Another Brand	FUSOTEC
5 min	84.7 %	95.6 %
30 min	60.4 %	75.2 %
Re-dispersibility	Hard-caking	Excellent

Alkaline Cleaner

Advantages

With special surfactant compounded, cleaning well the slurry (and the colloidal silica-base) developed by lapping or polishing process. preventing reattachment of the smudge, less residue or stain on the plate after cleaning by good rinsing performance. Suitable for detergent for compound semiconductor board as silicone plate, a variety of ceramic plate and LT plate.

Grinding Fluid

Advantages

To be used as grinding fluid for O.F. or edge of sapphire ingot. Keeping extremely sharp cutting edge with preventing clogging on the diamond cut wheel by excellent performance of lubricity, ant-foaming, surface tension and rust prevention.